



(51) International Patent Classification:
H01L 33/48 (2010.01) H01L 21/60 (2006.01)
H01L 33/62 (2010.01) H01L 33/00 (2010.01)
H01L 33/38 (2010.01)

(21) International Application Number:
PCT/IB2010/050748

(22) International Filing Date:
19 February 2010 (19.02.2010)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
12/397,367 4 March 2009 (04.03.2009) US

(71) Applicants (for all designated States except US):
PHILIPS LUMILEDS LIGHTING COMPANY, LLC
[US/US]; 370 West Trimble Road MS 91/MG, San Jose,
California 95131 (US). KONINKLIJKE PHILIPS
ELECTRONICS N.V. [NL/NL]; Groenewoudseweg 1,
NL-5621 BA Eindhoven (NL).

(72) Inventors; and

(75) Inventors/Applicants (for US only): NEFF, James G.
[US/US]; MS 91/MG, 370 West Trimble Road, San Jose,
California 95131 (US). EPLER, John E. [US/US]; MS
91/MG, 370 West Trimble Road, San Jose, California
95131 (US). SCHIAFFINO, Stefano [US/US]; MS
91/MG, 370 West Trimble Road, San Jose, California
95131 (US).

(74) Agents: BEKKERS, Joost, J.J. et al.; High Tech Cam-
pus Building 44, NL-5656 AE Eindhoven (NL).

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,

AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO,
DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP,
KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD,
ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI,
NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD,
SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR,
TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ,
TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE,
ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV,
MC, MK, MT, NL, NO, PL, PT, RO, SE, SI, SK, SM,
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW,
ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

- as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))
- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))

Published:

- with international search report (Art. 21(3))
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments (Rule 48.2(h))

(88) Date of publication of the international search report:
28 October 2010

(54) Title: METHOD OF BONDING A SEMICONDUCTOR DEVICE USING A COMPLIANT BONDING STRUCTURE

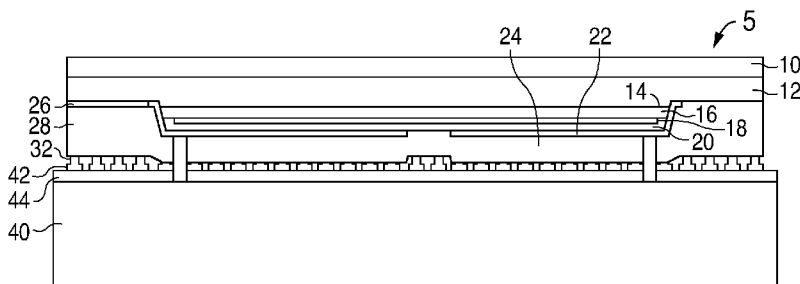


FIG. 5

(57) Abstract: A compliant bonding structure is disposed between a semiconductor device and a mount (40). In some embodiments, the device is a light emitting device. When the semiconductor light emitting device is attached to the mount, for example by providing ultrasonic energy to the semiconductor light emitting device, the compliant bonding structure collapses to partially fill a space between the semiconductor light emitting device and the mount. In some embodiments, the compliant bonding structure is plurality of metal bumps (32) that undergo plastic deformation during bonding. In some embodiments, the compliant bonding structure is a porous metal layer (46).

WO 2010/100577 A3

INTERNATIONAL SEARCH REPORT

International application No
PCT/IB2010/050748

A. CLASSIFICATION OF SUBJECT MATTER		
INV.	H01L33/48	H01L33/62
		H01L33/38
		H01L21/60
ADD.	H01L33/00	
According to International Patent Classification (IPC) or to both national classification and IPC		
B. FIELDS SEARCHED		
Minimum documentation searched (classification system followed by classification symbols) H01L		
Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched		
Electronic data base consulted during the international search (name of data base and, where practical, search terms used) EPO-Internal		
C. DOCUMENTS CONSIDERED TO BE RELEVANT		
Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2008/054290 A1 (SHIEH YUH-REN [TW] ET AL) 6 March 2008 (2008-03-06) paragraph [0017]; figures 2,3,6,7	1-6,8,9,11,14,15
Y	-----	7,12,13
Y	US 5 904 499 A (PACE BENEDICT G [US]) 18 May 1999 (1999-05-18) figure 7b	7
Y	-----	7
Y	WO 2006/013800 A1 (MATSUSHITA ELECTRIC IND CO LTD [JP]; UEMOTO TAKAARI; NAITO HIROYUKI) 9 February 2006 (2006-02-09) abstract; figures	12,13
Y	US 6 455 878 B1 (BHAT JEROME CHANDRA [US] ET AL) 24 September 2002 (2002-09-24) column 3, line 50 - column 4, line 8; claim 2; figures 2,4	

	-/--	
<input checked="" type="checkbox"/>	Further documents are listed in the continuation of Box C.	<input checked="" type="checkbox"/>
		See patent family annex.
* Special categories of cited documents :		
"A" document defining the general state of the art which is not considered to be of particular relevance	"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention	
"E" earlier document but published on or after the international filing date	"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone	
"L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)	"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art.	
"O" document referring to an oral disclosure, use, exhibition or other means	"&" document member of the same patent family	
"P" document published prior to the international filing date but later than the priority date claimed		
Date of the actual completion of the international search	Date of mailing of the international search report	
20 May 2010	27/08/2010	
Name and mailing address of the ISA/ European Patent Office, P.B. 5818 Patentlaan 2 NL - 2280 HV Rijswijk Tel. (+31-70) 340-2040. Fax: (+31-70) 340-3016	Authorized officer Ott, André	

INTERNATIONAL SEARCH REPORT

International application No
PCT/IB2010/050748

C(Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	US 2007/176288 A1 (DAUBENSPECK TIMOTHY H [US] ET AL DAUBENSPECK TIMOTHY HARRISON [US] ET) 2 August 2007 (2007-08-02) abstract; figures 1gi,2 -----	12, 13
A	JP 09 064238 A (OKI ELECTRIC IND CO LTD) 7 March 1997 (1997-03-07) abstract; figure 1 -----	7, 12
A	US 2007/057271 A1 (SCHIAFFINO STEFANO [US] ET AL SCHIAFFINO STEFANO [US] ET AL) 15 March 2007 (2007-03-15) paragraph [0021] - paragraph [0022]; figures 4,7,8 -----	7, 12, 15
A	US 2002/179921 A1 (COHN MICHAEL B [US]) 5 December 2002 (2002-12-05) figures -----	12-15

INTERNATIONAL SEARCH REPORT

International application No.
PCT/IB2010/050748

Box No. II Observations where certain claims were found unsearchable (Continuation of item 2 of first sheet)

This international search report has not been established in respect of certain claims under Article 17(2)(a) for the following reasons:

- 1. Claims Nos.:
because they relate to subject matter not required to be searched by this Authority, namely:

- 2. Claims Nos.:
because they relate to parts of the international application that do not comply with the prescribed requirements to such an extent that no meaningful international search can be carried out, specifically:

- 3. Claims Nos.:
because they are dependent claims and are not drafted in accordance with the second and third sentences of Rule 6.4(a).

Box No. III Observations where unity of invention is lacking (Continuation of item 3 of first sheet)

This International Searching Authority found multiple inventions in this international application, as follows:

see additional sheet

- 1. As all required additional search fees were timely paid by the applicant, this international search report covers all searchable claims.

- 2. As all searchable claims could be searched without effort justifying an additional fees, this Authority did not invite payment of additional fees.

- 3. As only some of the required additional search fees were timely paid by the applicant, this international search report covers only those claims for which fees were paid, specifically claims Nos.:

- 4. No required additional search fees were timely paid by the applicant. Consequently, this international search report is restricted to the invention first mentioned in the claims; it is covered by claims Nos.:

3-9, 15(completely); 1, 2, 11-14(partially)

Remark on Protest

- The additional search fees were accompanied by the applicant's protest and, where applicable, the payment of a protest fee.
- The additional search fees were accompanied by the applicant's protest but the applicable protest fee was not paid within the time limit specified in the invitation.
- No protest accompanied the payment of additional search fees.

FURTHER INFORMATION CONTINUED FROM PCT/ISA/ 210

This International Searching Authority found multiple (groups of) inventions in this international application, as follows:

1. claims: 3-9, 15(completely); 1, 2, 11-14(partially)

Method of bonding a semiconductor device and a mount using micro-bumps having different desitys on different contacts.

2. claims: 10(completely); 1, 2, 11-14(partially)

Method of bonding a semiconductor device and a mount using posous metal layer as a compliant bonding structure.

INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No

PCT/IB2010/050748

Patent document cited in search report		Publication date	Patent family member(s)	Publication date
US 2008054290	A1	06-03-2008	NONE	
US 5904499	A	18-05-1999	NONE	
WO 2006013800	A1	09-02-2006	EP 1794809 A1 JP 2006074007 A US 2009039376 A1	13-06-2007 16-03-2006 12-02-2009
US 6455878	B1	24-09-2002	EP 1258929 A2 JP 4488669 B2 JP 2003031858 A TW 541729 B	20-11-2002 23-06-2010 31-01-2003 11-07-2003
US 2007176288	A1	02-08-2007	NONE	
JP 9064238	A	07-03-1997	NONE	
US 2007057271	A1	15-03-2007	CN 101263614 A EP 1927142 A1 WO 2007031893 A1 JP 2007081417 A US 2008142833 A1	10-09-2008 04-06-2008 22-03-2007 29-03-2007 19-06-2008
US 2002179921	A1	05-12-2002	NONE	